

**THERMAL ENHANCED EXTENDED SURFACE TAPE FOR INTEGRATED  
CIRCUIT HEAT DISSIPATION**

**ABSTRACT OF THE DISCLOSURE**

- 5           A thermal conductive tape article is provided which is adhered to the surface  
of an integrated circuit device to dissipate heat from the device. The thermal  
conductive tape article is preferably corrugated and may have a number of  
configurations providing an expanded surface area. The corrugated tape article may  
also have a metal strip bonded to one or both sides of the tape article to form a single-  
10   faced or double-faced corrugated tape article. The tape article is preferably made of  
copper or aluminum.

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